

Product Summary

$V_{(BR)DSS}$	$R_{DS(on) \max}$	I_D $T_A = +25^\circ\text{C}$
100V	125m Ω @ $V_{GS} = 10\text{V}$	4.0A
	150m Ω @ $V_{GS} = 6.0\text{V}$	3.7A

Description

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

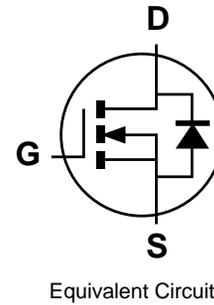
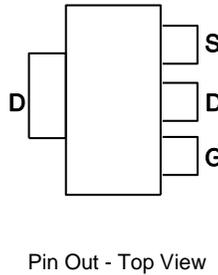
- DC Motor Control
- DC-AC Inverters

Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: SOT223
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram Below
- Terminals: Finish - Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.112 grams (Approximate)

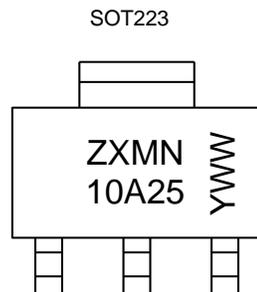


Ordering Information (Note 4)

Part Number	Qualification	Case	Packaging
ZXMN10A25GTA	Standard	SOT223	1,000 / Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



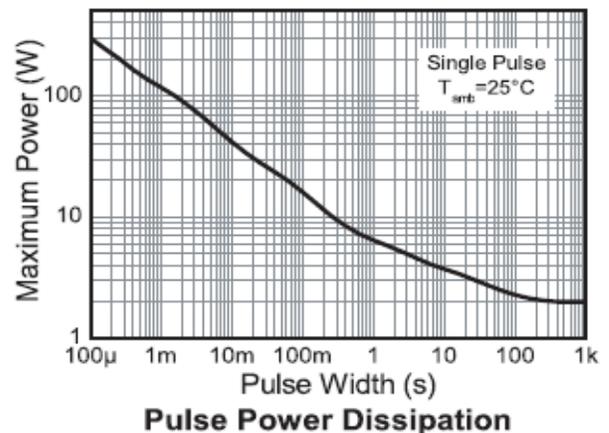
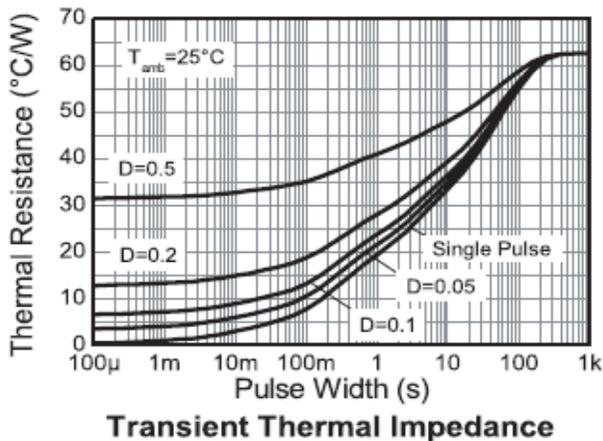
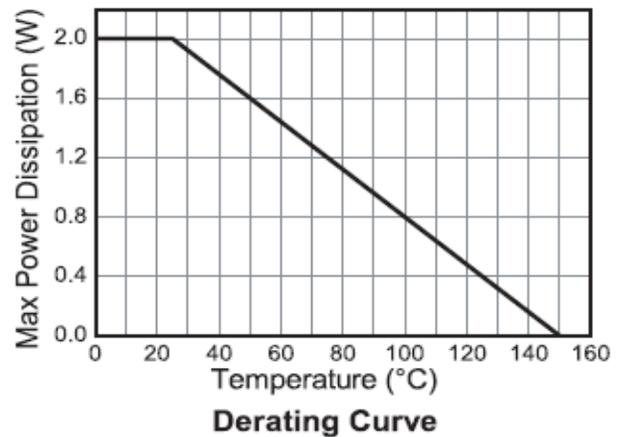
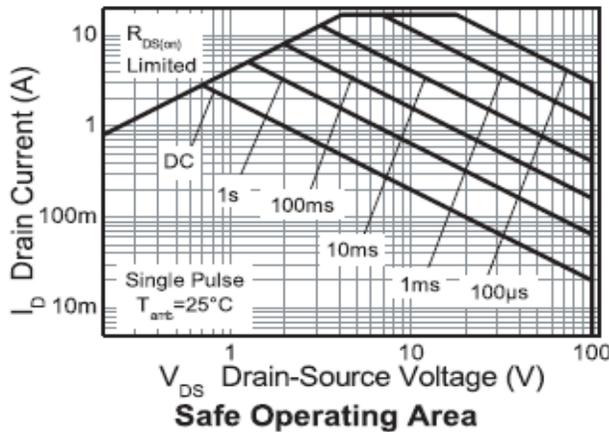
ZXMN 10A25 = Product Type Marking Code
 YWW = Date Code Marking
 Y or \bar{Y} = Last Digit of Year (ex: 5= 2015)
 WW or $\bar{W}W$ = Week Code (01-53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Drain-Source Voltage	V _{DS}	100	V	
Gate-Source Voltage	V _{GS}	±20	V	
Continuous Drain Current, V _{GS} = 10V, t ≤ 10 sec	I _D	T _A = +25°C	4.0	A
		T _A = +70°C	3.2	A
Continuous Drain Current (Note 5) V _{GS} = 10V	I _D	2.9	A	
Maximum Continuous Body Diode Forward Current (Note 5)	I _S	5.4	A	
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I _{DM}	17	A	
Pulsed Source Current (10µs pulse, duty cycle = 1%)	I _{SM}	17	A	

Thermal Resistance (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5), T _A = +25°C	P _D	2.0	W
Linear Derating Factor		16	mW/°C
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	62.5	°C/W
Total Power Dissipation (Note 5), T _A = +25°C, t ≤ 10 seconds	P _D	3.9	W
Linear Derating Factor		31	mW/°C
Thermal Resistance, Junction to Ambient, t ≤ 10 seconds (Note 5)	R _{θJA}	32	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

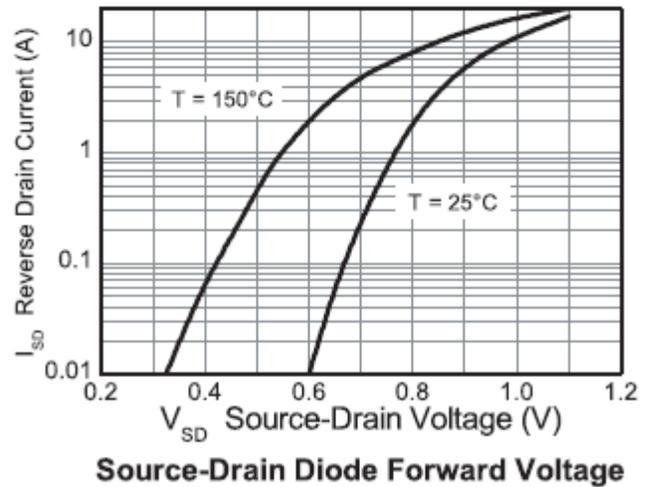
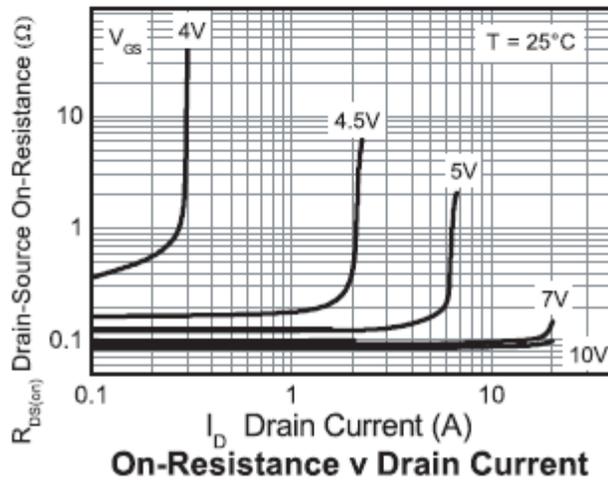
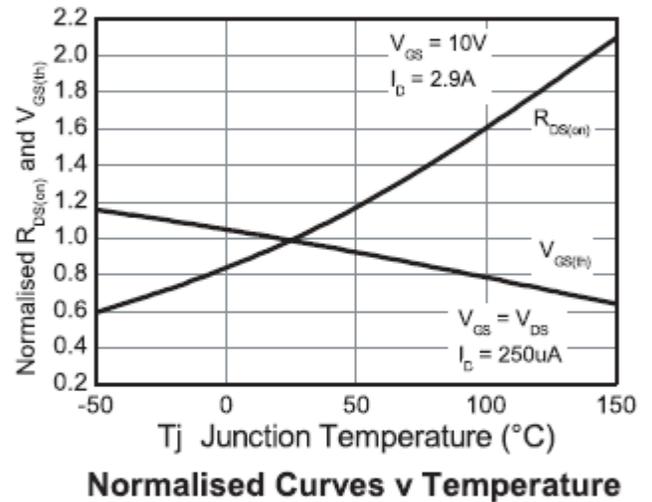
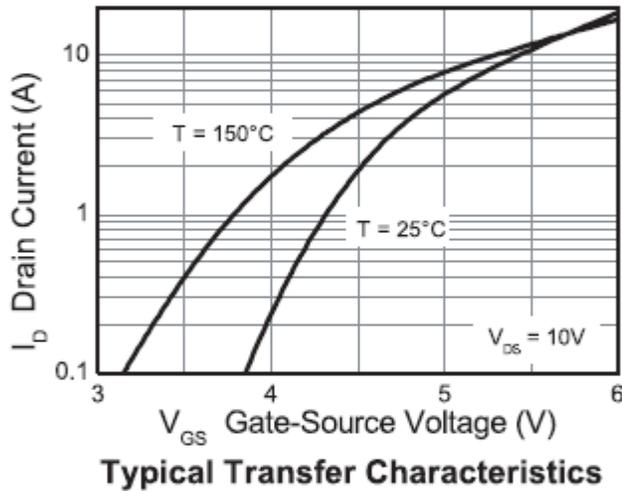
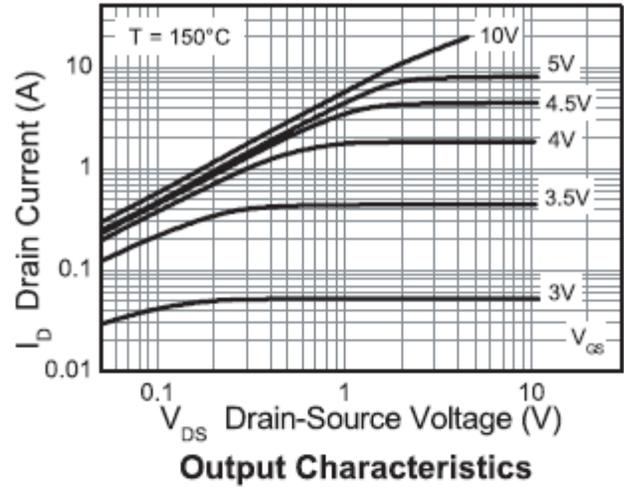
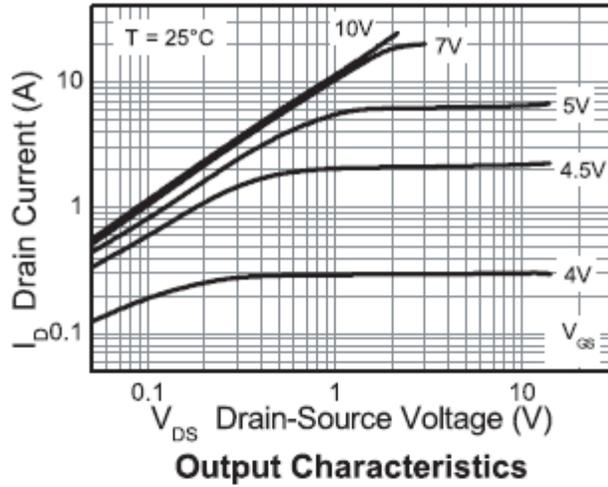
Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)


Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

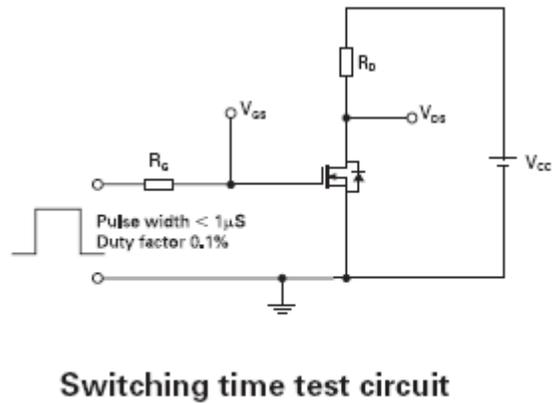
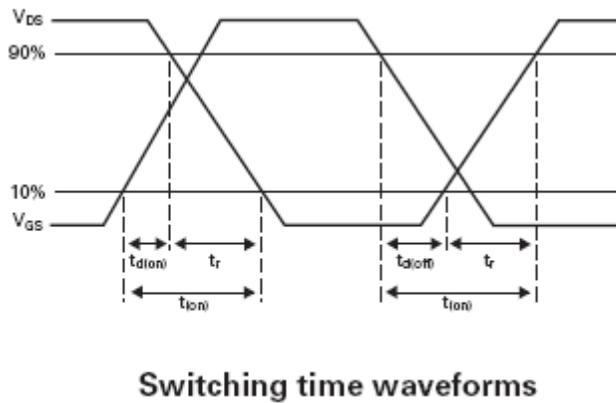
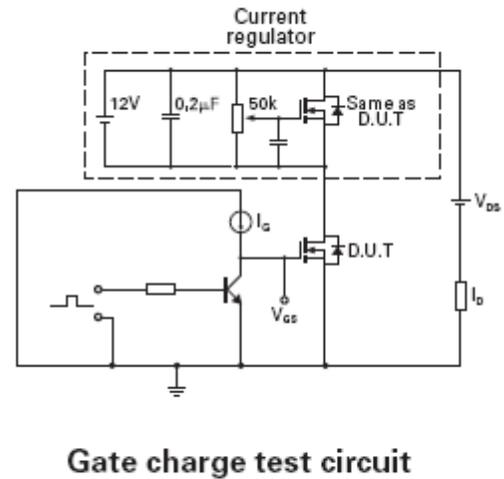
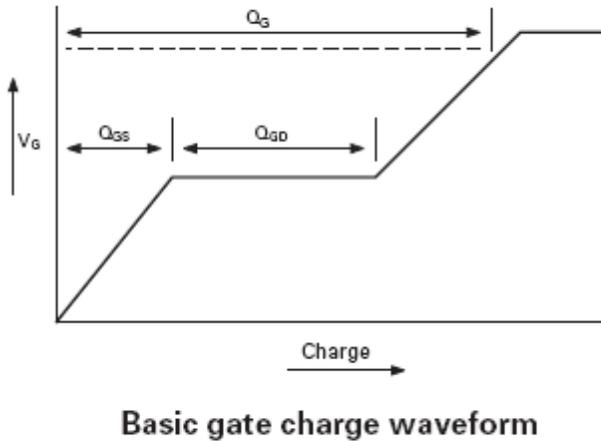
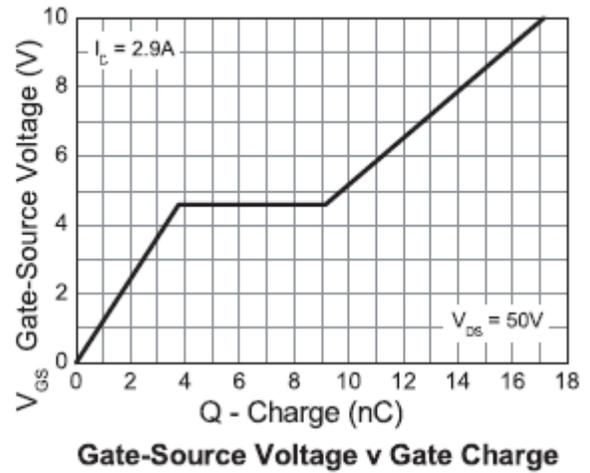
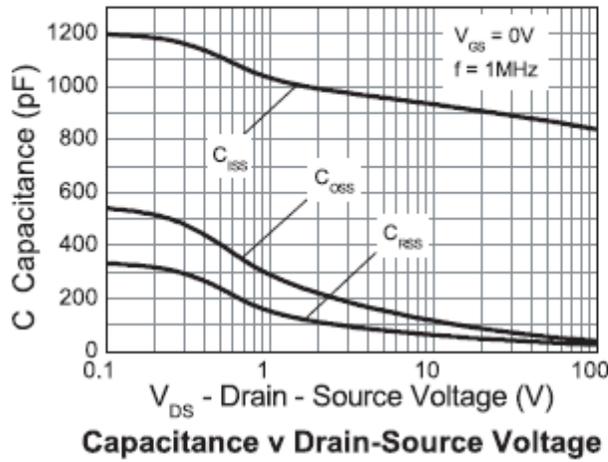
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV _{DSS}	100	—	—	V	V _{GS} = 0V, I _D = 250μA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	0.5	μA	V _{DS} = 100V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	V _{GS(th)}	2.0	—	4.0	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(on)}	—	—	125	mΩ	V _{GS} = 10V, I _D = 2.9A
		—	—	150		V _{GS} = 6.0V, I _D = 2.6A
Forward Transfer Admittance	Y _{fs}	—	7.3	—	S	V _{DS} = 15V, I _D = 2.9A
Diode Forward Voltage	V _{SD}	—	0.85	0.95	V	V _{GS} = 0V, I _S = 4.0A
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C _{iss}	—	859	—	pF	V _{DS} = 50V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{oss}	—	57	—		
Reverse Transfer Capacitance	C _{rss}	—	33	—		
Total Gate Charge	Q _g	—	9.6	—	nC	V _{DS} = 50V, V _{GS} = 5.0V, I _D = 2.9A
Total Gate Charge	Q _g	—	17	—	nC	V _{DS} = 50V, V _{GS} = 10V, I _D = 2.9A
Gate-Source Charge	Q _{gs}	—	3.8	—		
Gate-Drain Charge	Q _{gd}	—	5.4	—		
Turn-On Delay Time	t _{D(on)}	—	4.9	—	ns	V _{DS} = 50V, V _{GS} = 10V, I _D = 1.0 A, R _G = 6.0Ω
Turn-On Rise Time	t _r	—	3.7	—		
Turn-Off Delay Time	t _{D(off)}	—	18	—		
Turn-Off Fall Time	t _f	—	9.4	—		
Body Diode Reverse Recovery Time	t _{rr}	—	40.5	—	ns	V _{GS} = 0V, I _S = 2.9A,
Body Diode Reverse Recovery Charge	Q _{rr}	—	62	—	nC	di/dt = 100A/μs

- Notes:
5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1-inch square copper plate
 6. Short duration pulse test used to minimize self-heating effect.
 7. Guaranteed by design. Not subject to production testing.

Typical Characteristics

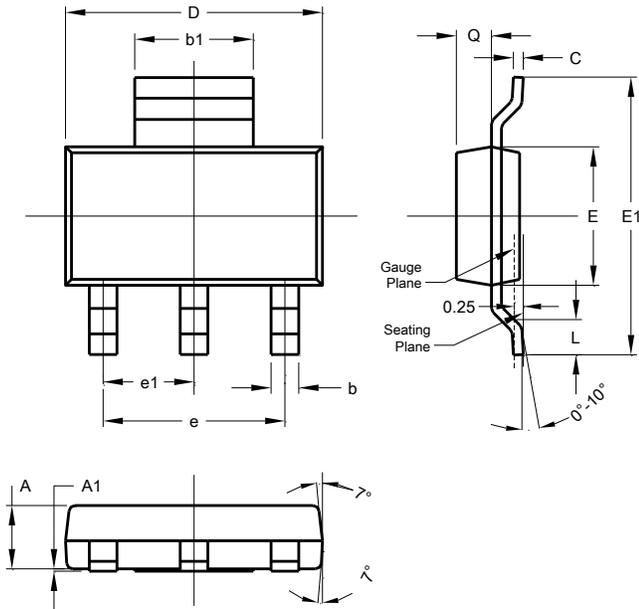


Typical Characteristics



Package Outline Dimensions

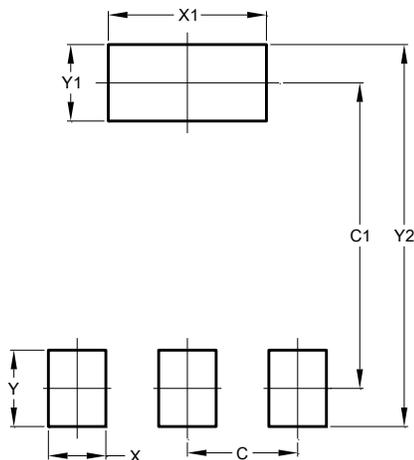
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOT223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b	0.60	0.80	0.70
b1	2.90	3.10	3.00
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	-	-	4.60
e1	-	-	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00

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